Layer Stacking

TOP

BOTTOM

Overall Board Thickness: 62 Mil
Soldermask Color: RED
Silkscreen Color: White
 Drill hole tolerance: +/- 3 Mil

<table>
<thead>
<tr>
<th>SIZE</th>
<th>QTY</th>
<th>SYM</th>
<th>PLATED</th>
<th>TOL</th>
</tr>
</thead>
<tbody>
<tr>
<td>122</td>
<td>4</td>
<td>x</td>
<td>NO</td>
<td>+/-0.0</td>
</tr>
<tr>
<td>13</td>
<td>93</td>
<td>h</td>
<td>YES</td>
<td>+/-0.0</td>
</tr>
<tr>
<td>47.24</td>
<td>4</td>
<td>d</td>
<td>NO</td>
<td>+/-0.0</td>
</tr>
<tr>
<td>35.04</td>
<td>32</td>
<td>x</td>
<td>NO</td>
<td>+/-0.0</td>
</tr>
<tr>
<td>25</td>
<td>5</td>
<td>Δ</td>
<td>YES</td>
<td>+/-0.0</td>
</tr>
<tr>
<td>19.69 x 47.24</td>
<td>2</td>
<td>t</td>
<td>YES</td>
<td>+/-0.0</td>
</tr>
</tbody>
</table>
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